



## Description

- Pad-Per-Hole both sides. Plated-thru holes.
- 0.080" diameter isolated solder pad around each hole on both sides.
- Unrestricted component placement and extended area for high density applications.

## Specifications

<b>Dimensions</b> (H x W x Thick)	4.00" x 6.00" x 0.062" (101.6mm x 152.4mm x 1.57mm)
<b>Hole Diameter</b>	0.042" (1.067mm) Plated Thru
<b>Grid</b>	0.100" x 0.100" (2.54mm x 2.54mm)
<b>Circuit Pattern</b>	Pad per hole - both sides
<b>Material</b>	FR4
<b>UL Flammability Class</b>	94V-0
<b>16 Pin DIP Capacity</b>	72
<b>Wire-Wrap Terminals</b>	T44, T46, T49, T68
<b>Solder Terminals</b>	T42-1, K24C, K31C
<b>Wire-Wrap Socket Pins</b>	R32

